

GOLD REMOVAL FROM ELECTRONIC COMPONENTS

ABSTRACT

In some embodiments, a method removes gold plating on an electronic component. The method includes forming a gold and solder mixture on the electronic component via a first incrementally controlled heating procedure; incrementally cooling the electronic component via a first cooling procedure; wicking part or all of the gold and solder mixture from the electronic component to a metallic screen via a second incrementally controlled heating procedure; and incrementally cooling the electronic component via a second cooling procedure.

Fig. 1